



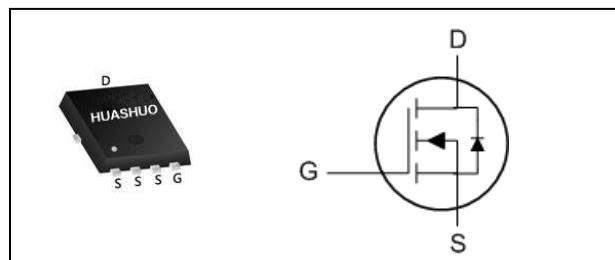
## Description

The HSBA0094 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the Synchronous Rectification for AC/DC Quick Charger.

## Product Summary

$V_{DS}$	100	V
$R_{DS(ON),max}$	11.5	mΩ
$I_D$	34	A

## PRPAK5X6 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current <sup>1</sup>	34	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current <sup>1</sup>	31	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	120	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	33	mJ
$I_{AS}$	Avalanche Current	15	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	56.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.2	°C/W



**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_{\text{D}}=250\mu\text{A}$	100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sub>2</sub>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_{\text{D}}=20\text{A}$	---	8	11.5	$\text{m}\Omega$
	Static Drain-Source On-Resistance <sub>2</sub>	$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_{\text{D}}=10\text{A}$	---	11.6	15	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_{\text{D}}=250\mu\text{A}$	1.2	---	2.4	V
$\text{I}_{\text{bss}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=80\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$\text{V}_{\text{DS}}=80\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=55^\circ\text{C}$	---	---	5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{Q}_g$	Total Gate Charge (10V)	$\text{V}_{\text{DS}}=50\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_{\text{D}}=20\text{A}$	---	43	---	$\text{nC}$
$\text{Q}_g$	Total Gate Charge (4.5V)		---	18.5	---	
$\text{Q}_{\text{GS}}$	Gate-Source Charge		---	8.5	---	
$\text{Q}_{\text{GD}}$	Gate-Drain Charge		---	10.3	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=50\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_G=3.3\Omega$ , $\text{I}_{\text{D}}=20\text{A}$	---	10	---	$\text{ns}$
$\text{T}_r$	Rise Time		---	7	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	50	---	
$\text{T}_f$	Fall Time		---	11	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=50\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3150	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	695	---	
$\text{Crss}$	Reverse Transfer Capacitance		---	25	---	

**Diode Characteristics**

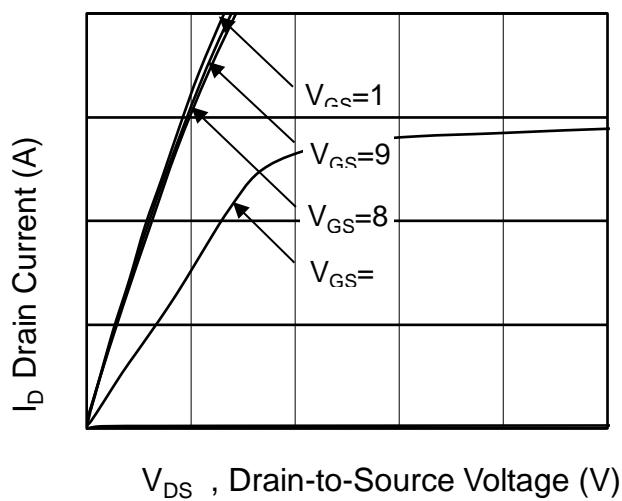
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sub>1,5</sub>	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$ , Force Current	---	---	34	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sub>2</sub>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_{\text{s}}=1\text{A}$ , $\text{T}_J=25^\circ\text{C}$	---	---	1.2	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time	$\text{I}_{\text{F}}=20\text{A}$ , $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$ , $\text{T}_J=25^\circ\text{C}$	---	45	---	nS
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		---	165	---	nC

Note :

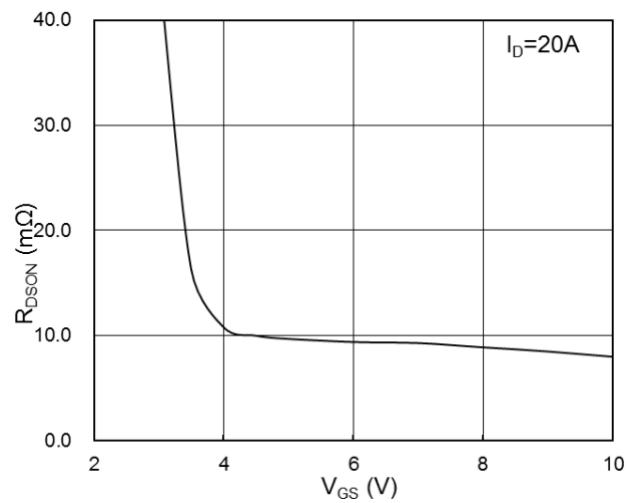
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=25\text{V}$ ,  $\text{V}_{\text{GS}}=10\text{V}$ ,  $\text{L}=0.3\text{mH}$ ,  $\text{I}_{\text{AS}}=15\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_{\text{D}}$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



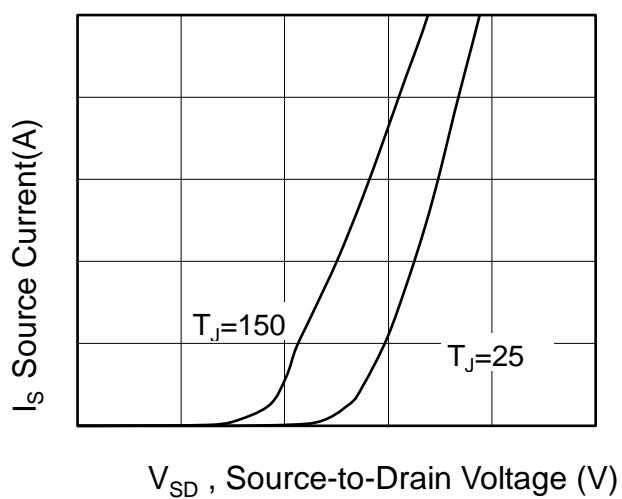
### Typical Characteristics



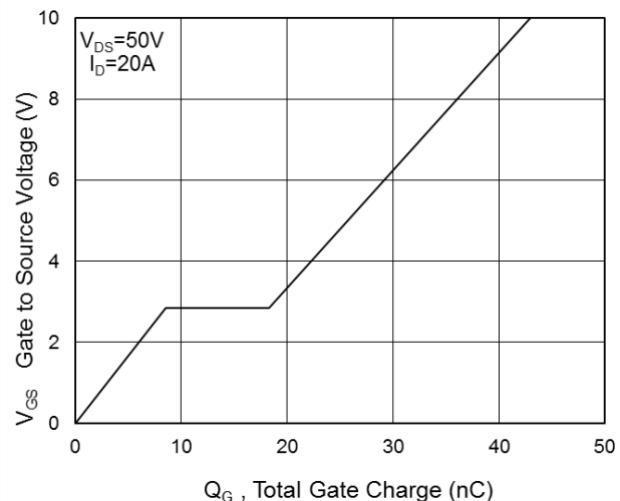
**Fig.1 Typical Output Characteristics**



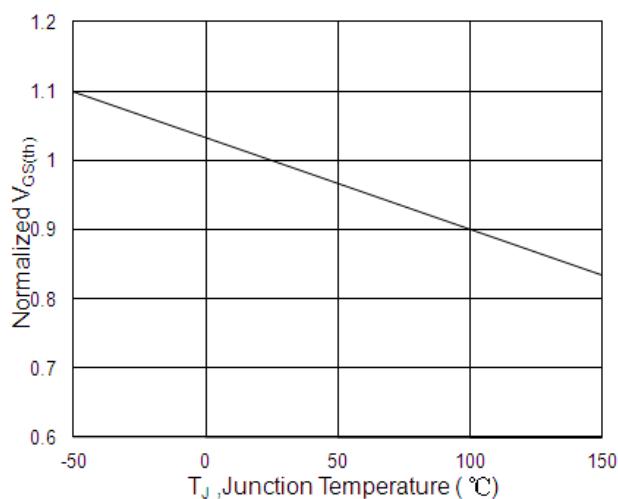
**Fig.2 On-Resistance vs. G-S Voltage**



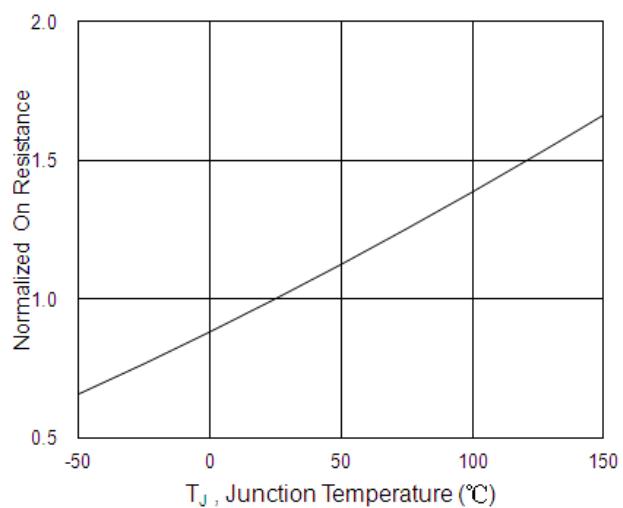
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**

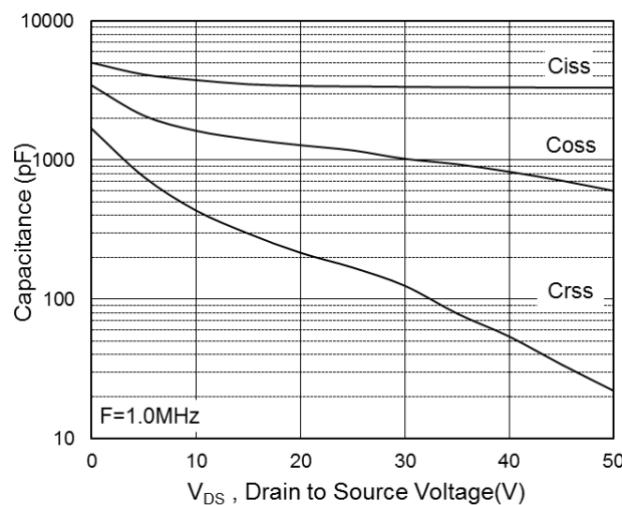


Fig.7 Capacitance

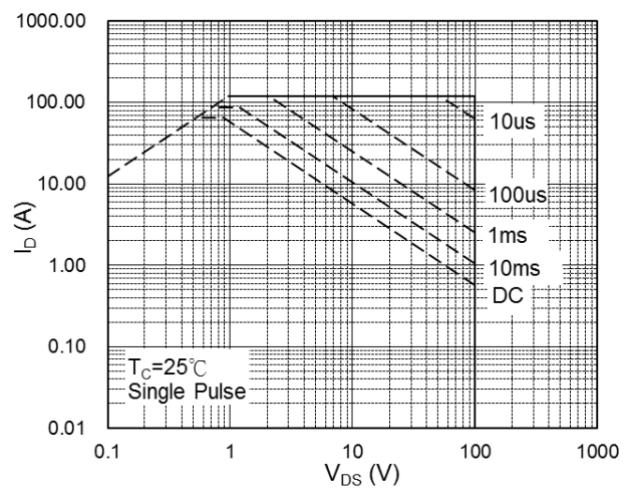


Fig.8 Safe Operating Area

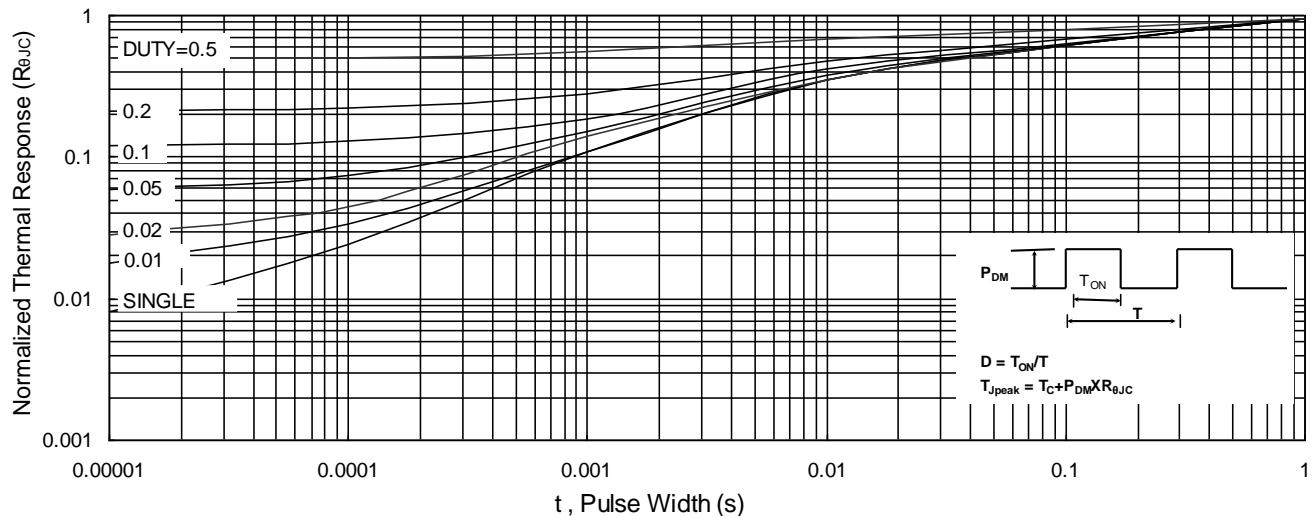


Fig.9 Normalized Maximum Transient Thermal Impedance

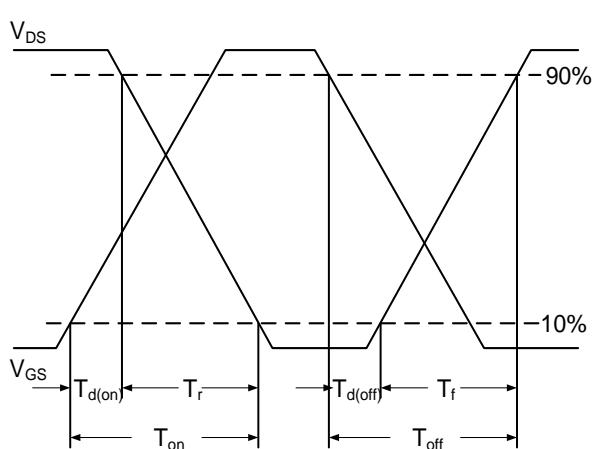


Fig.10 Switching Time Waveform

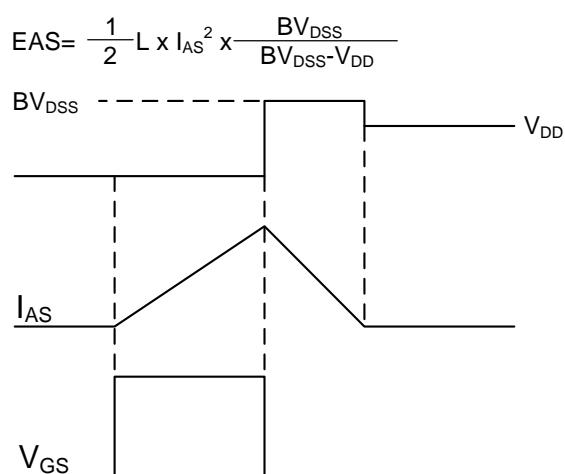
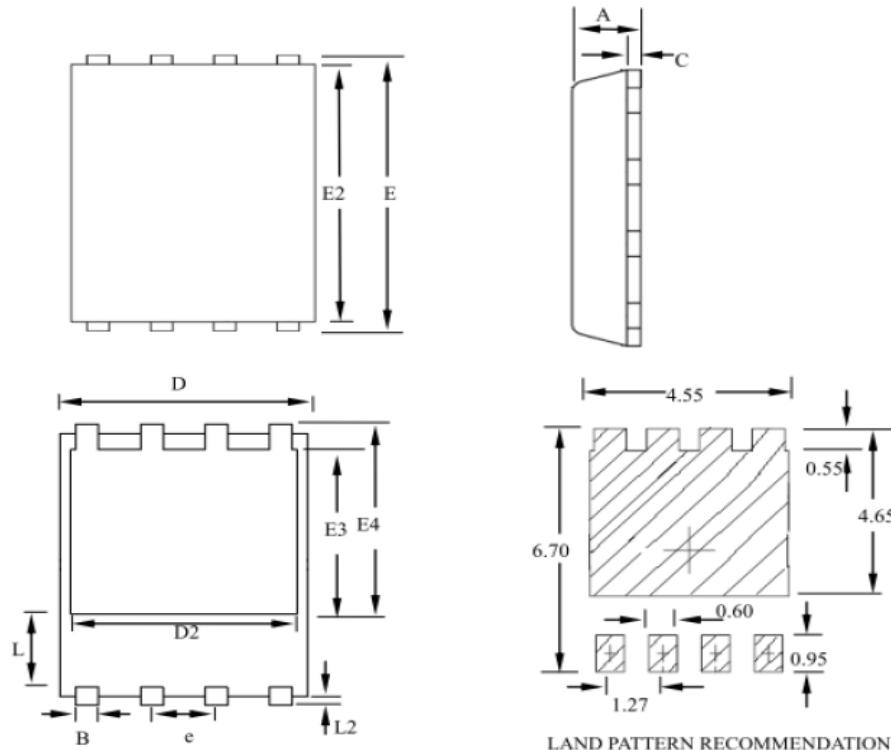


Fig.11 Unclamped Inductive Switching Waveform

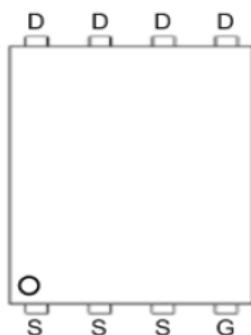


## Ordering Information

Part Number	Package code	Packaging
HSBA0094	PRPAK5*6	3000/Tape&Reel



LAND PATTERN RECOMMENDATION



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145	--	0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--